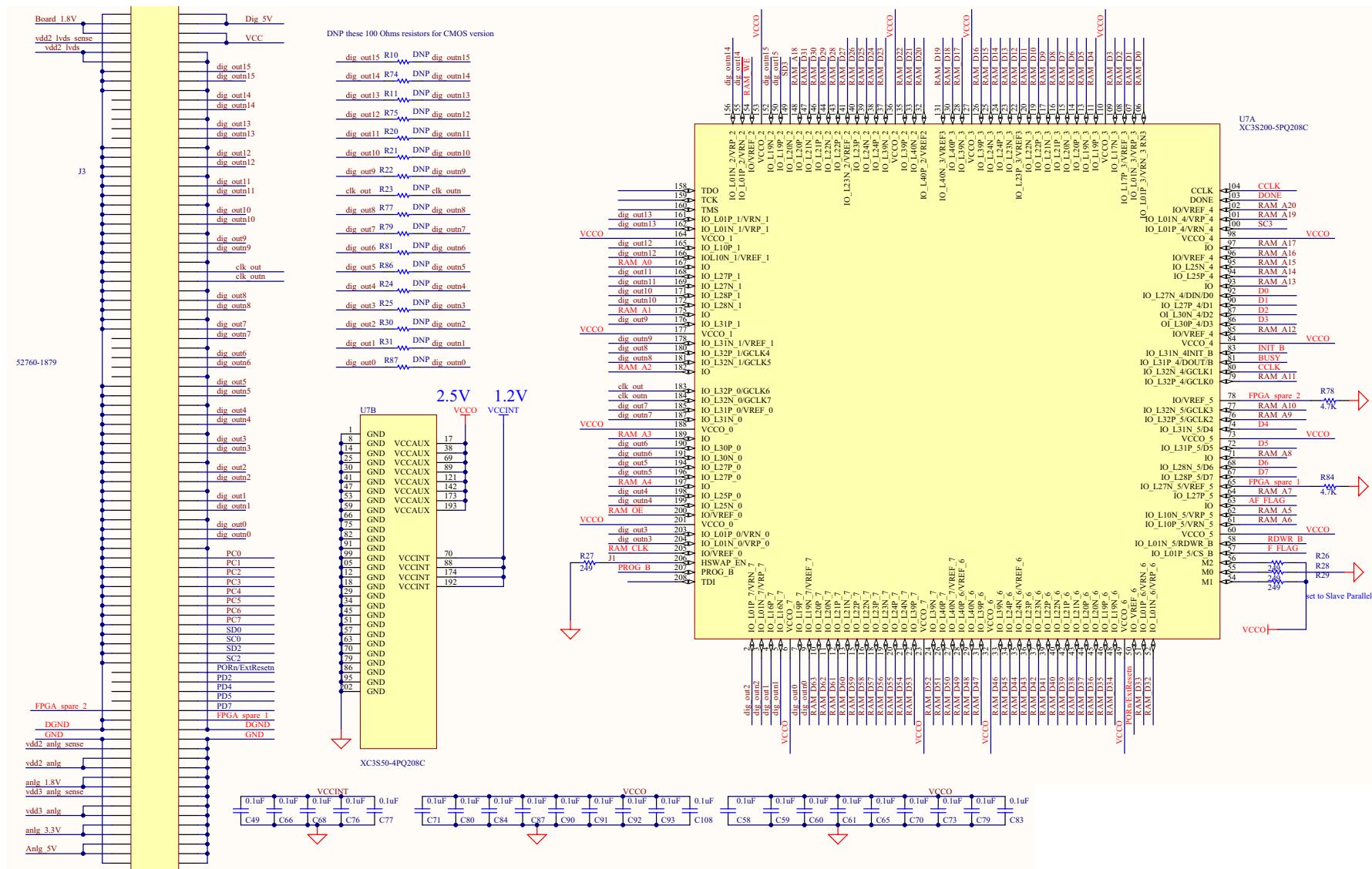
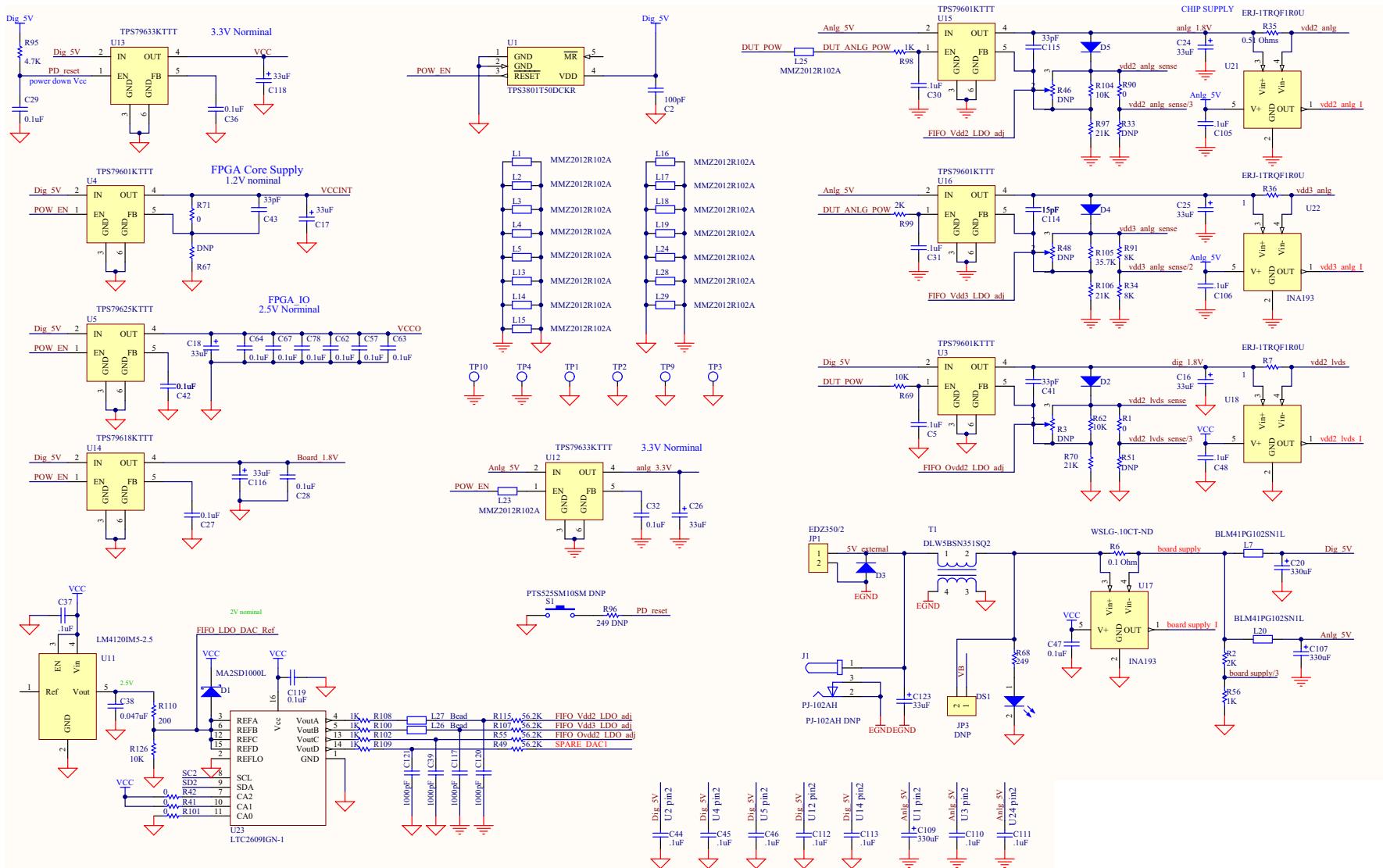


*KMB001CEVAL Schematics*



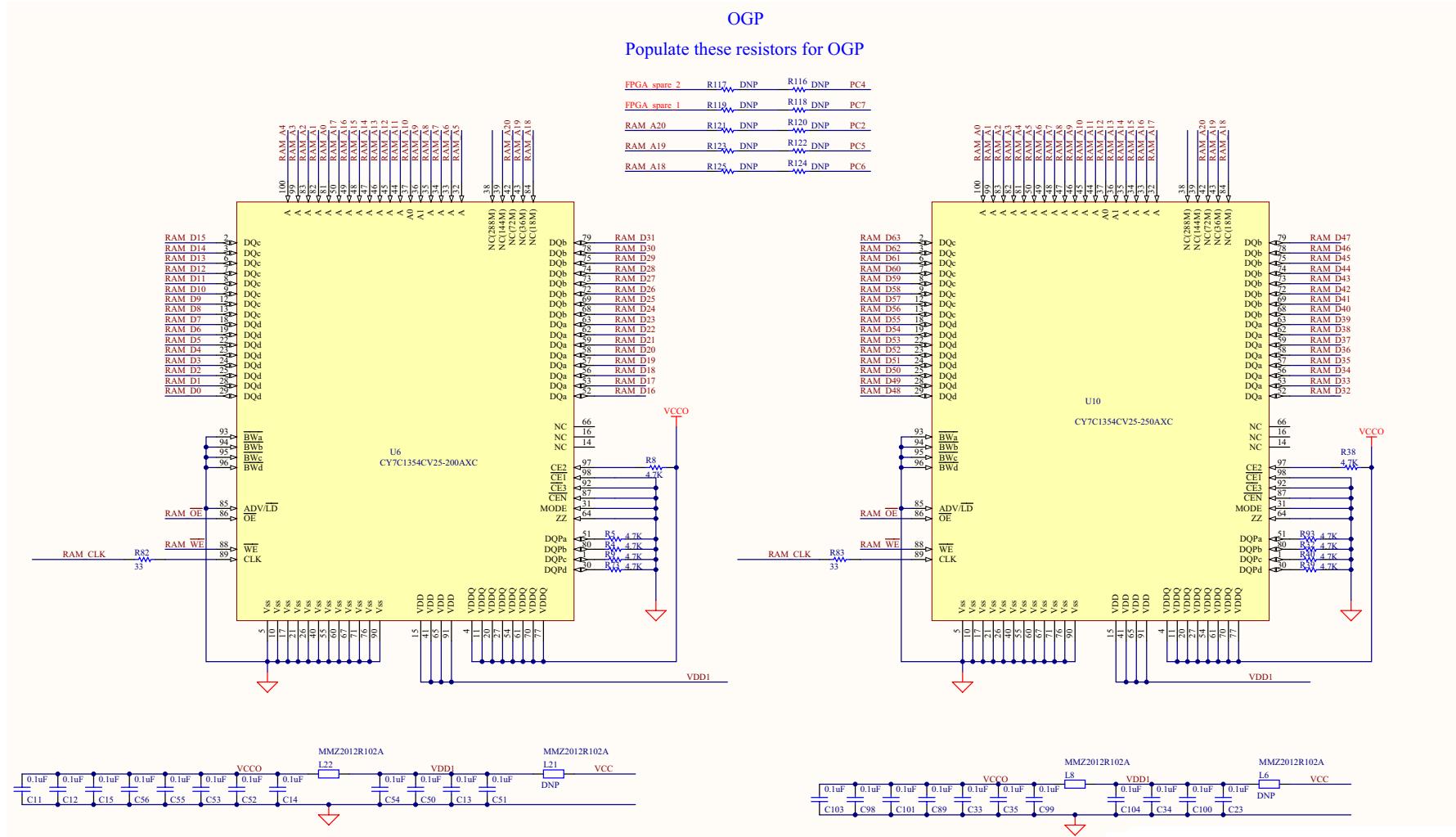
**FIGURE 1. FPGA, INPUT/OUTPUT MEZZANINE CONNECTOR**

## **KMB001CEVAL Schematics (Continued)**



**FIGURE 2. POWER**

**KMB001CEVAL Schematics (Continued)**



**FIGURE 3. MEMORY**

## KMB001CEVAL Schematics (Continued)

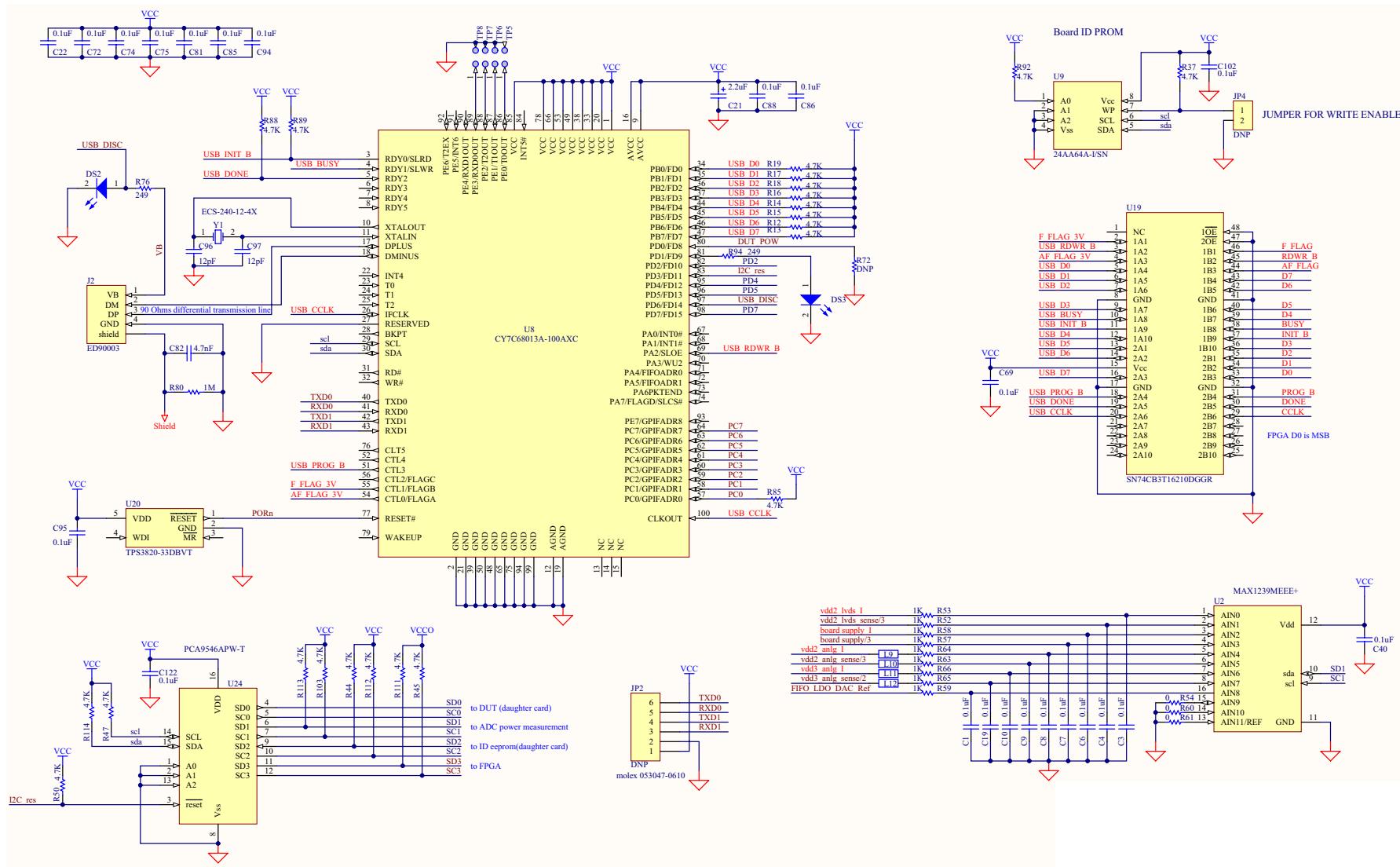
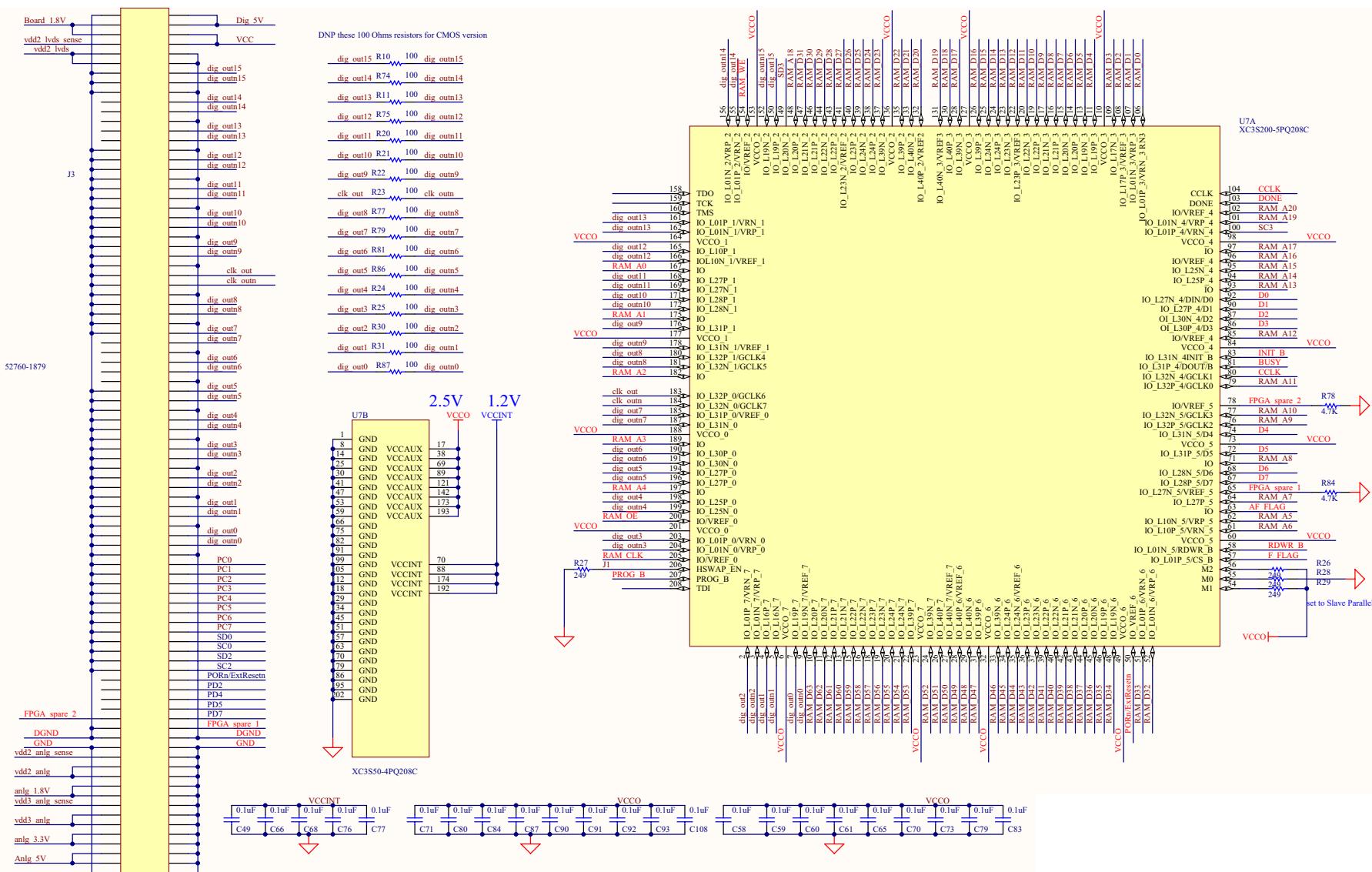


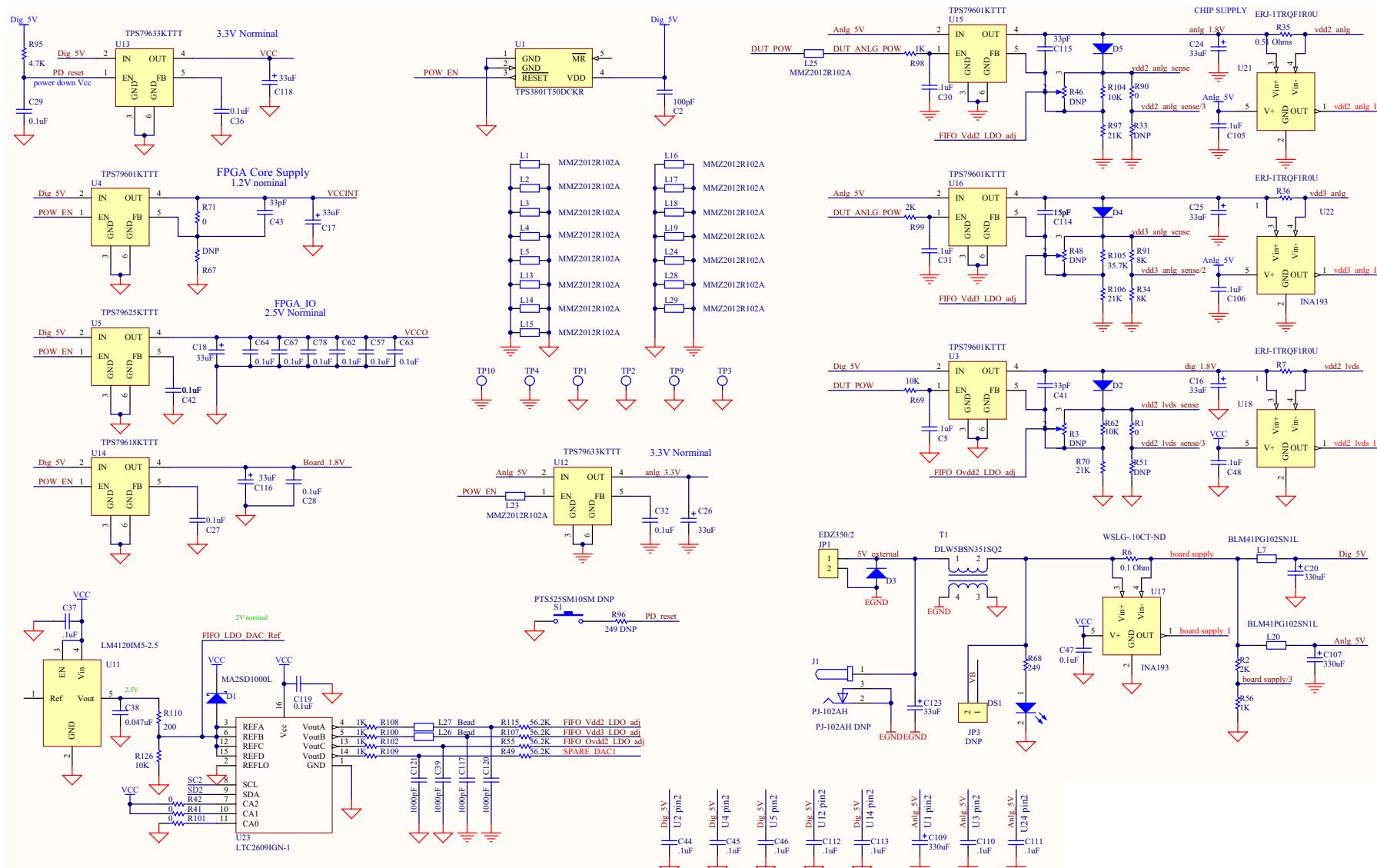
FIGURE 4. USB, MISC.

## **KMB001LEVAL Schematics**



**FIGURE 5. FPGA, INPUT/OUTPUT MEZZANINE CONNECTOR**

## **KMB001LEVAL Schematics (Continued)**

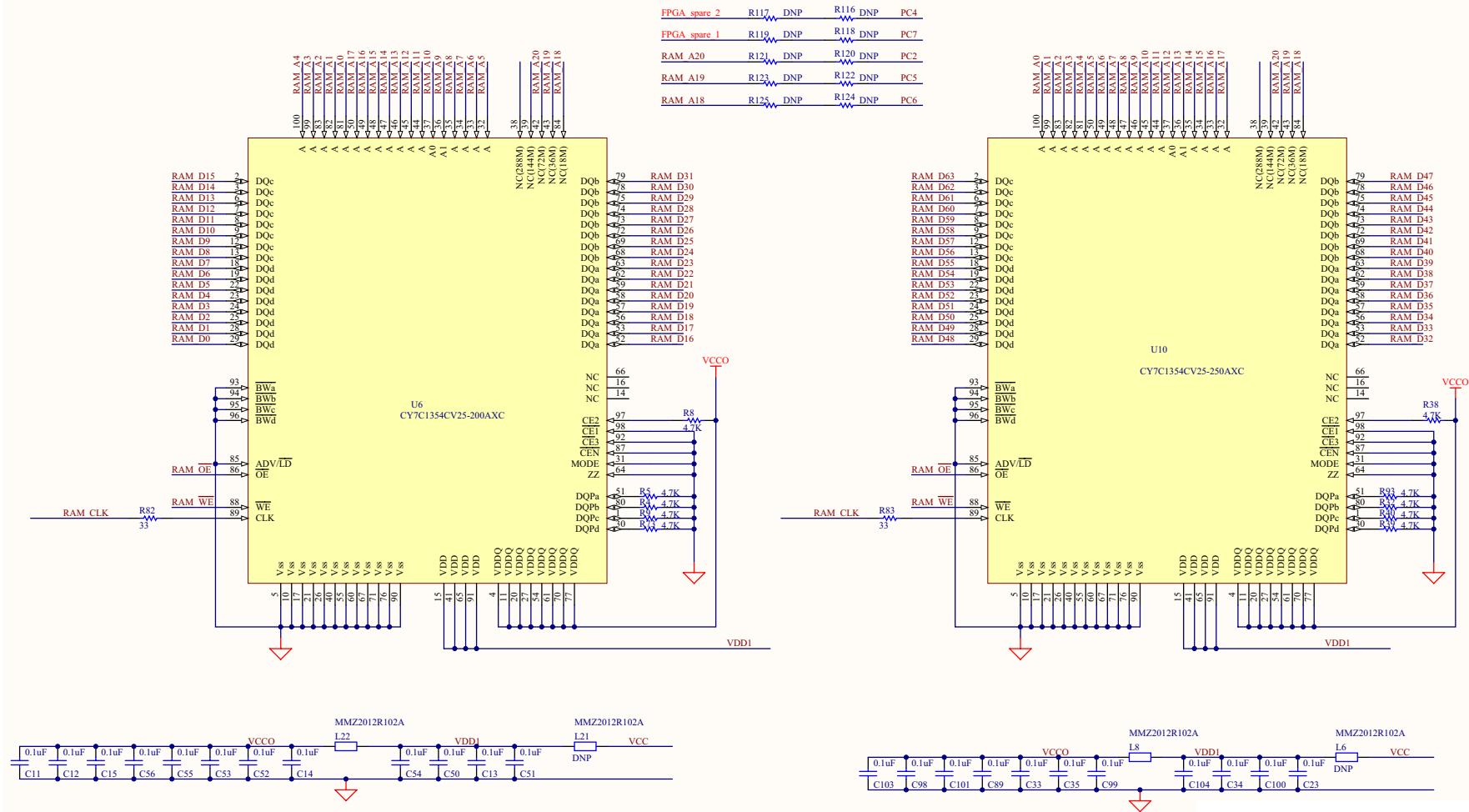


**FIGURE 6. POWER**

## **KMB001LEVAL Schematics (Continued)**

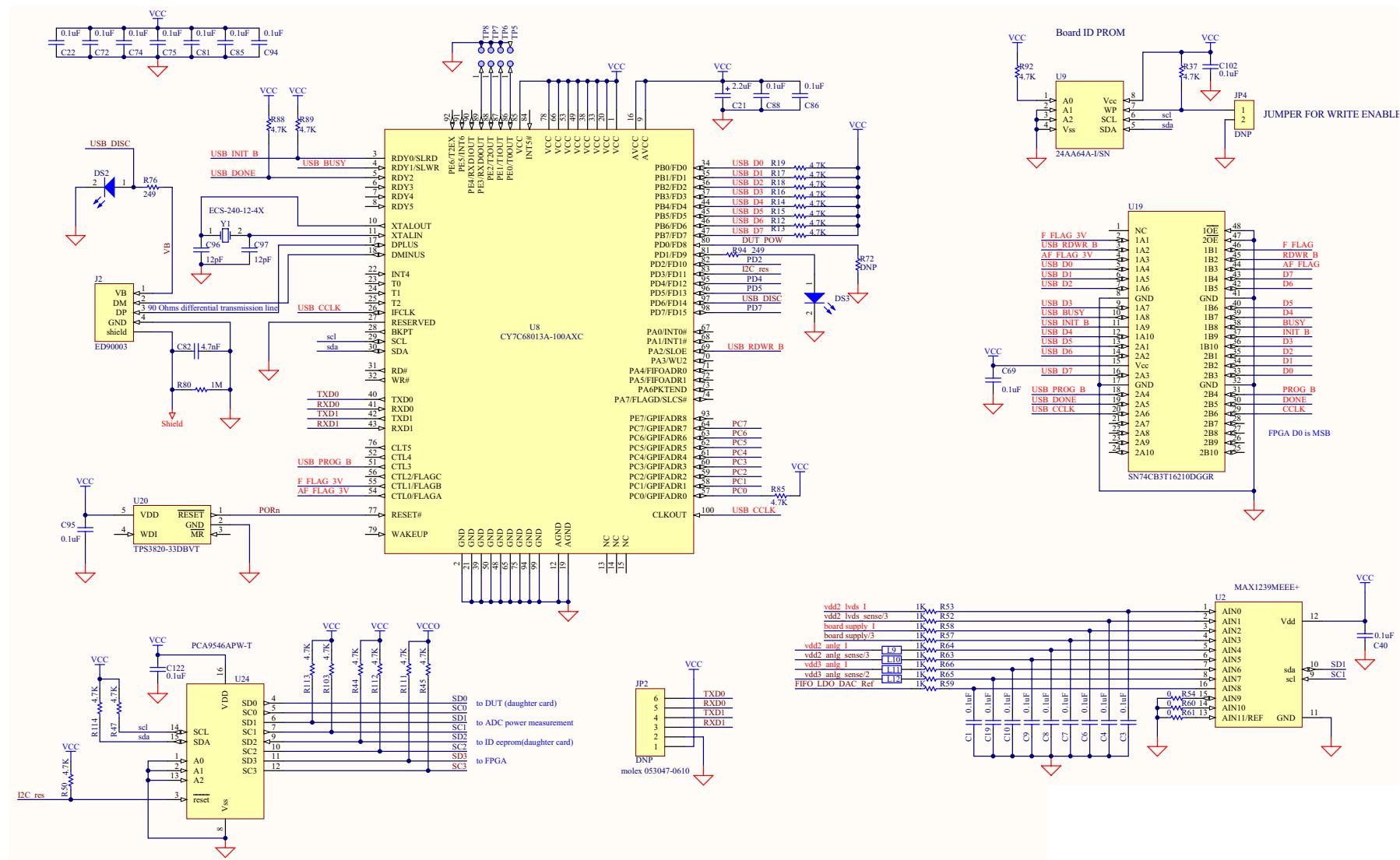
OGP

Populate these resistors for OGP



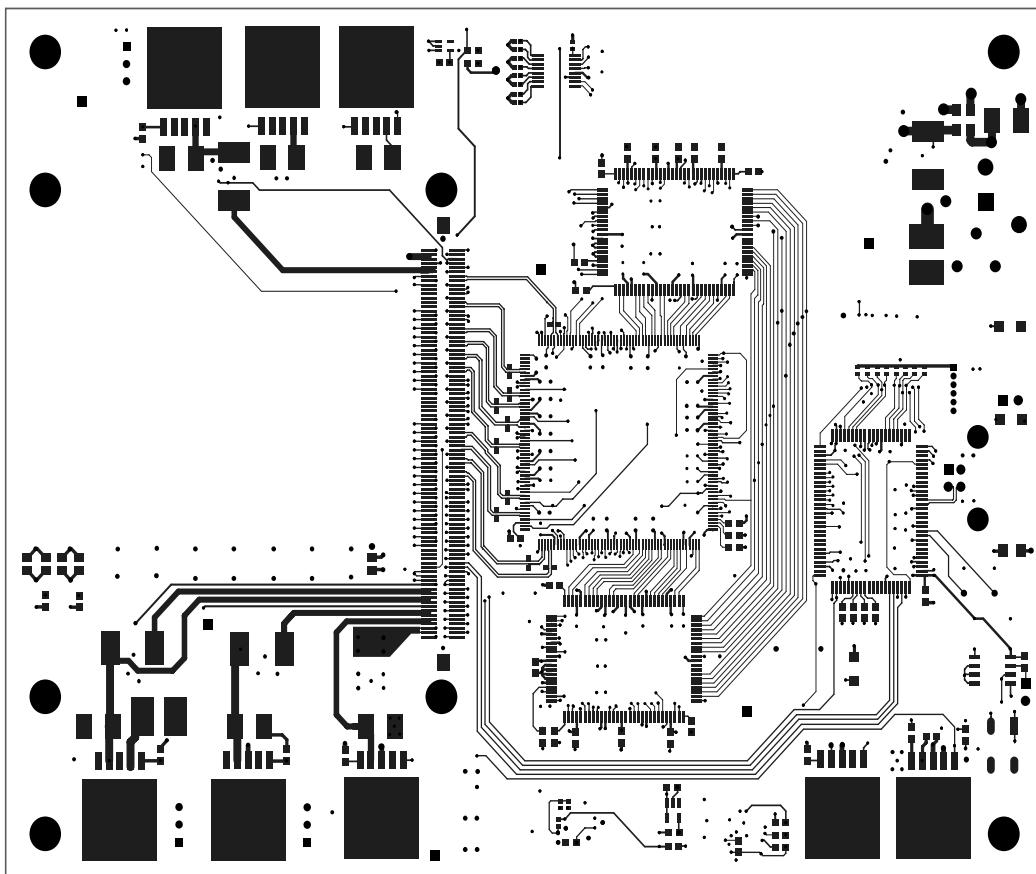
**FIGURE 7. MEMORY**

## **KMB001LEVAL Schematics (Continued)**



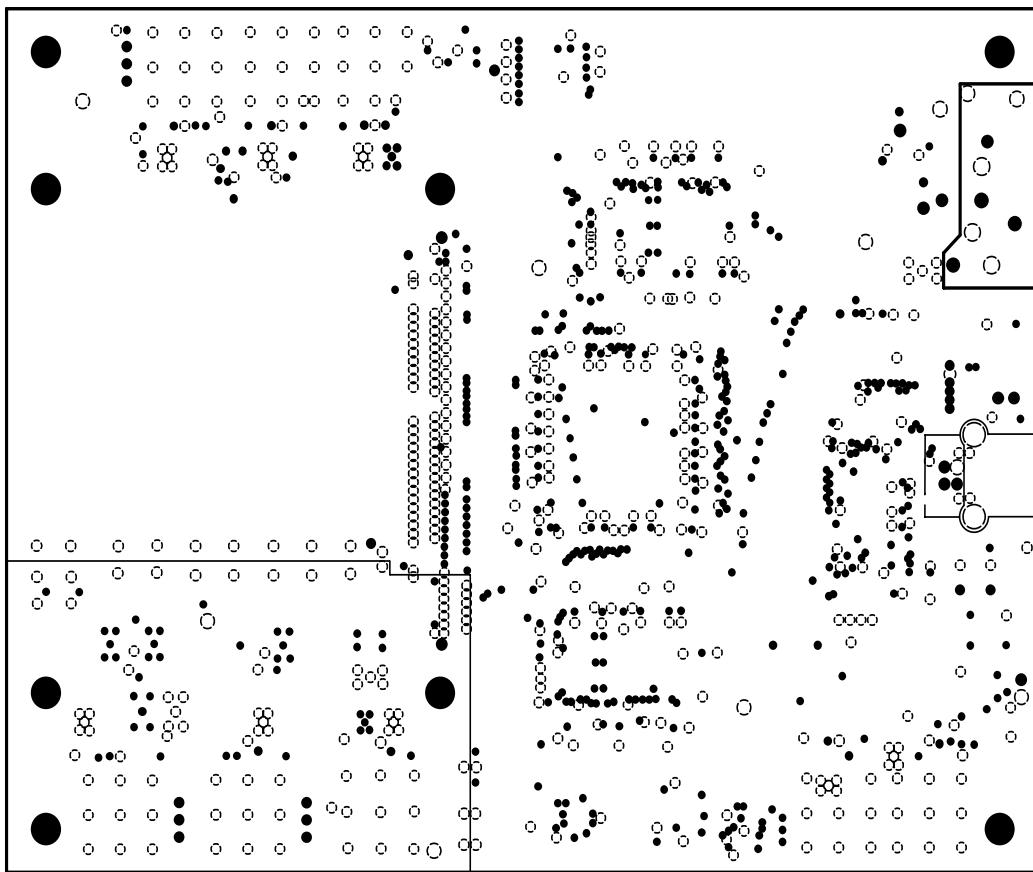
**FIGURE 8. USB, MISC.**

**KMB001CEVAL Layers**



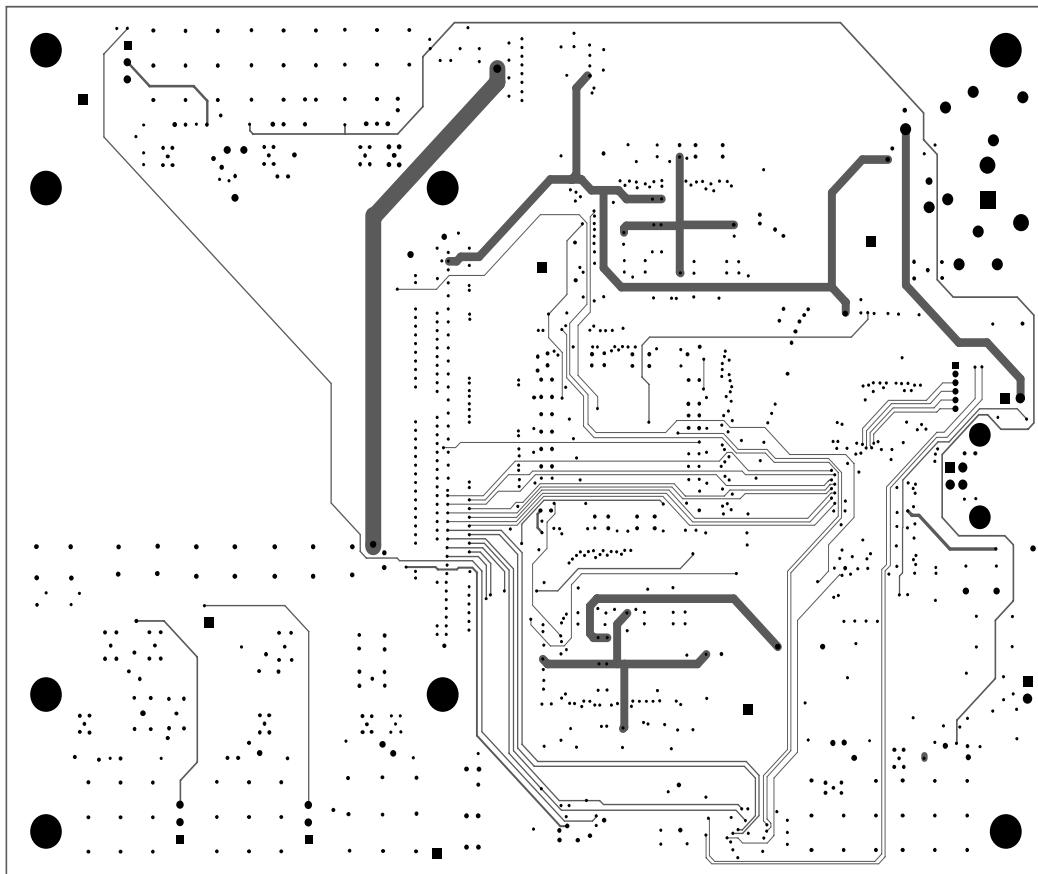
**FIGURE 9. TOP LAYER**

**KMB001CEVAL Layers (Continued)**



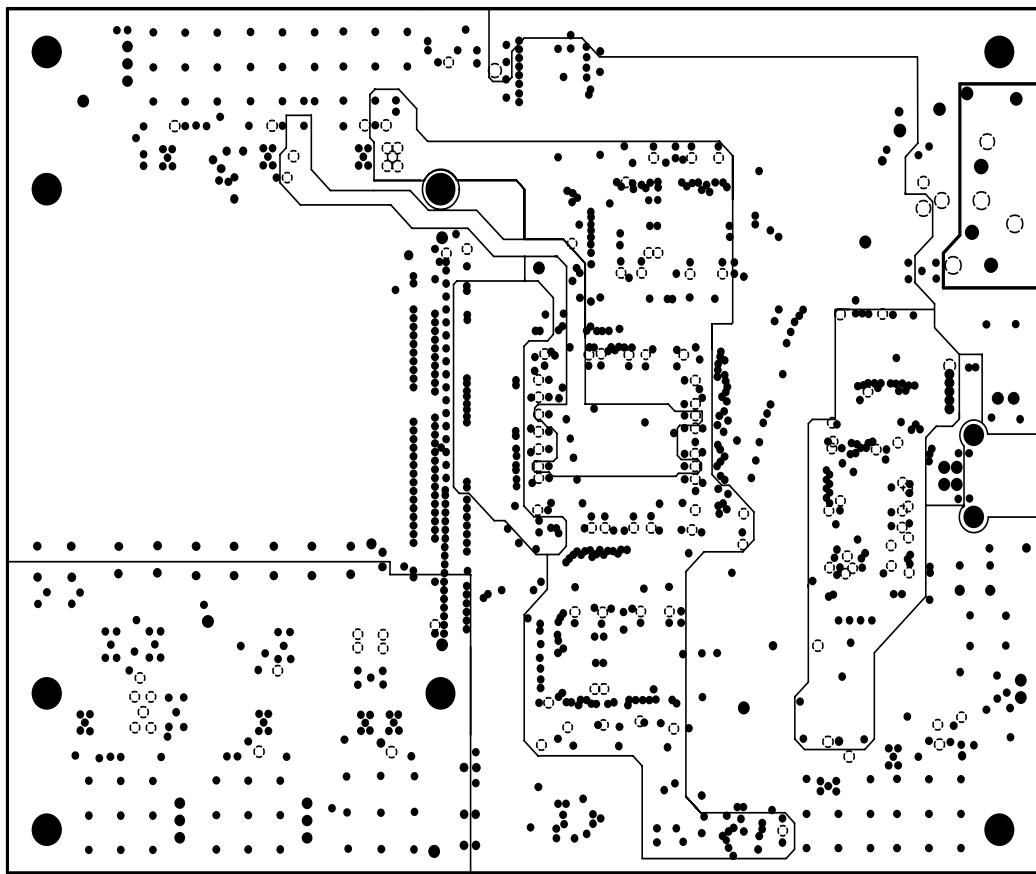
**FIGURE 10. GND PLANE**

**KMB001CEVAL Layers (Continued)**



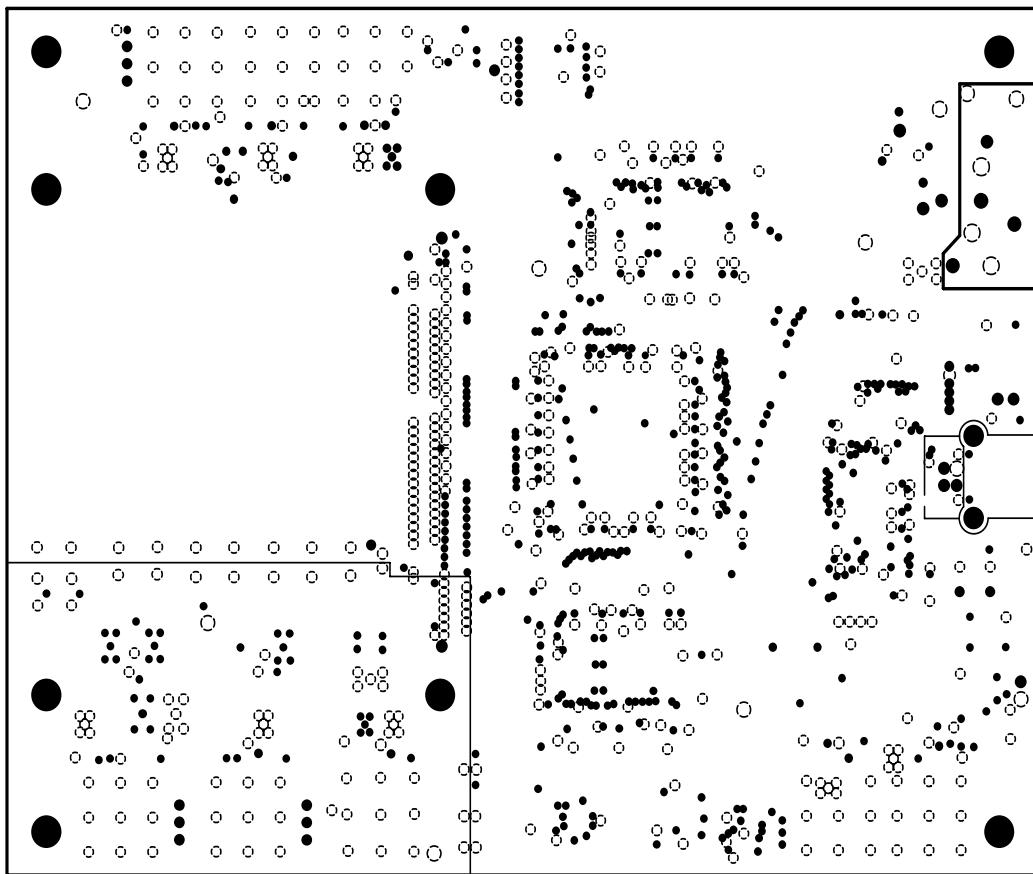
**FIGURE 11. MID LAYER 1**

**KMB001CEVAL Layers (Continued)**



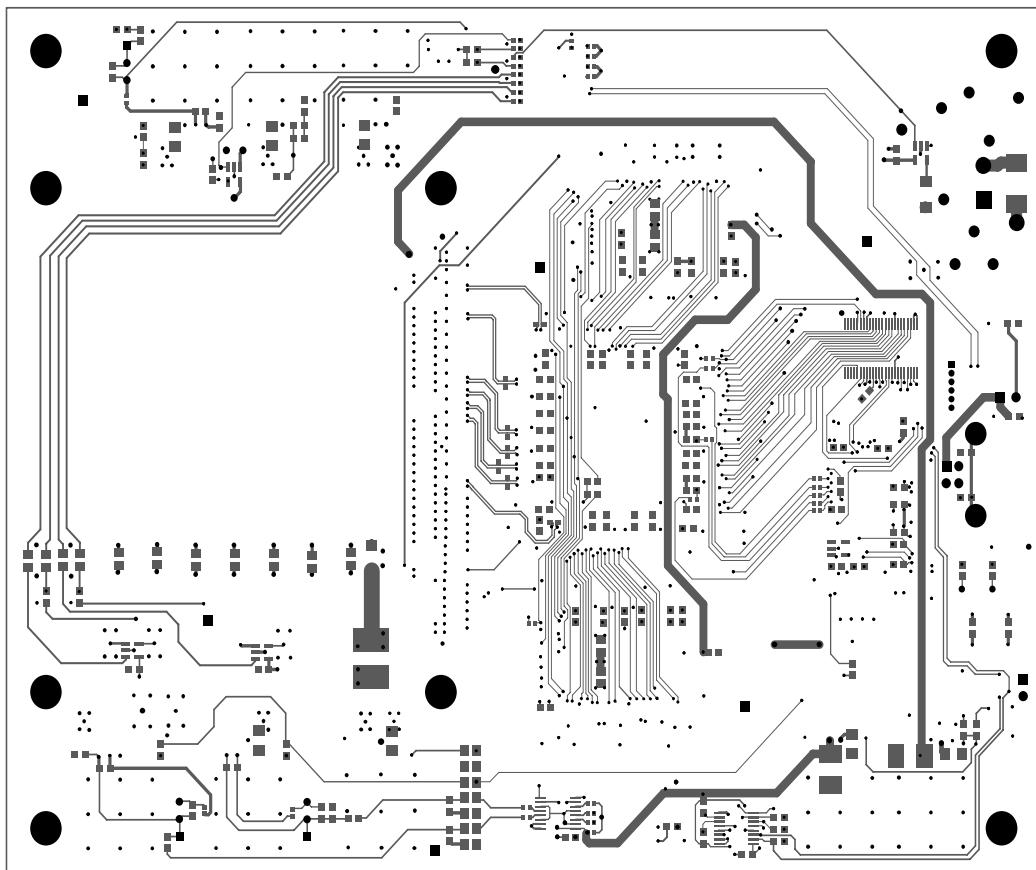
**FIGURE 12. POWER PLANE**

**KMB001CEVAL Layers (Continued)**

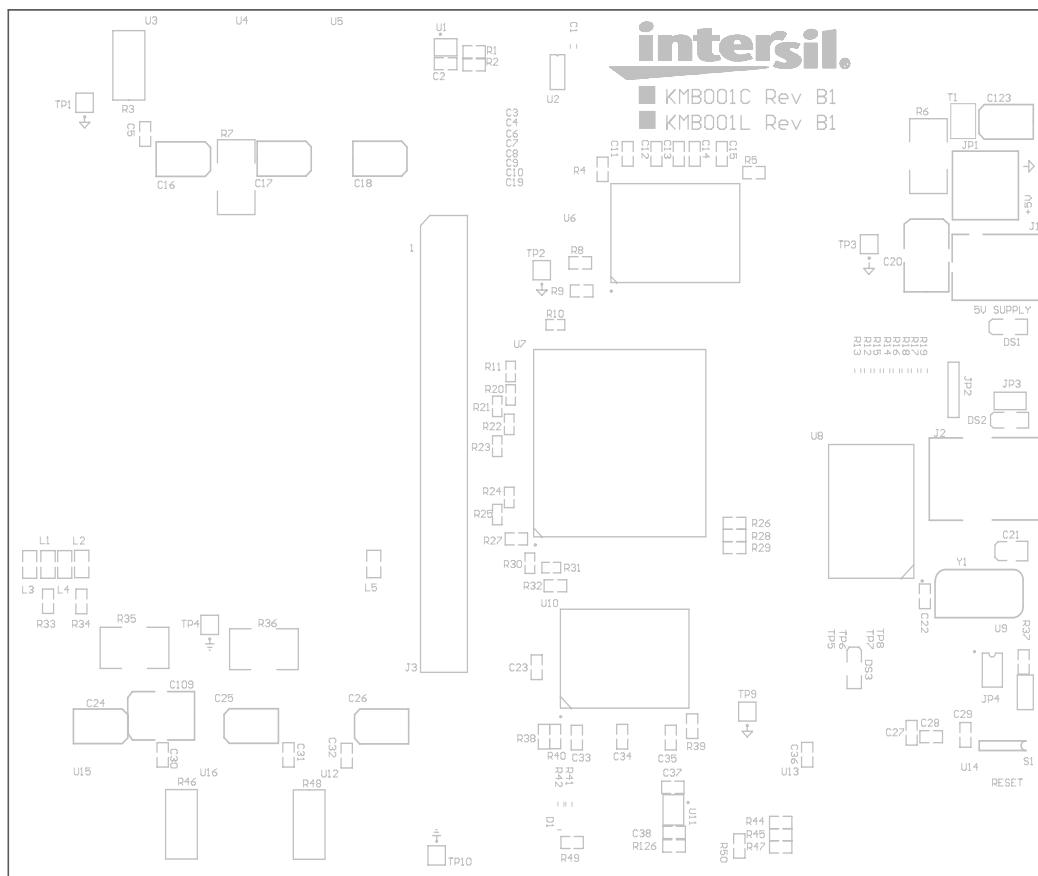


**FIGURE 13. GND PLANE 2**

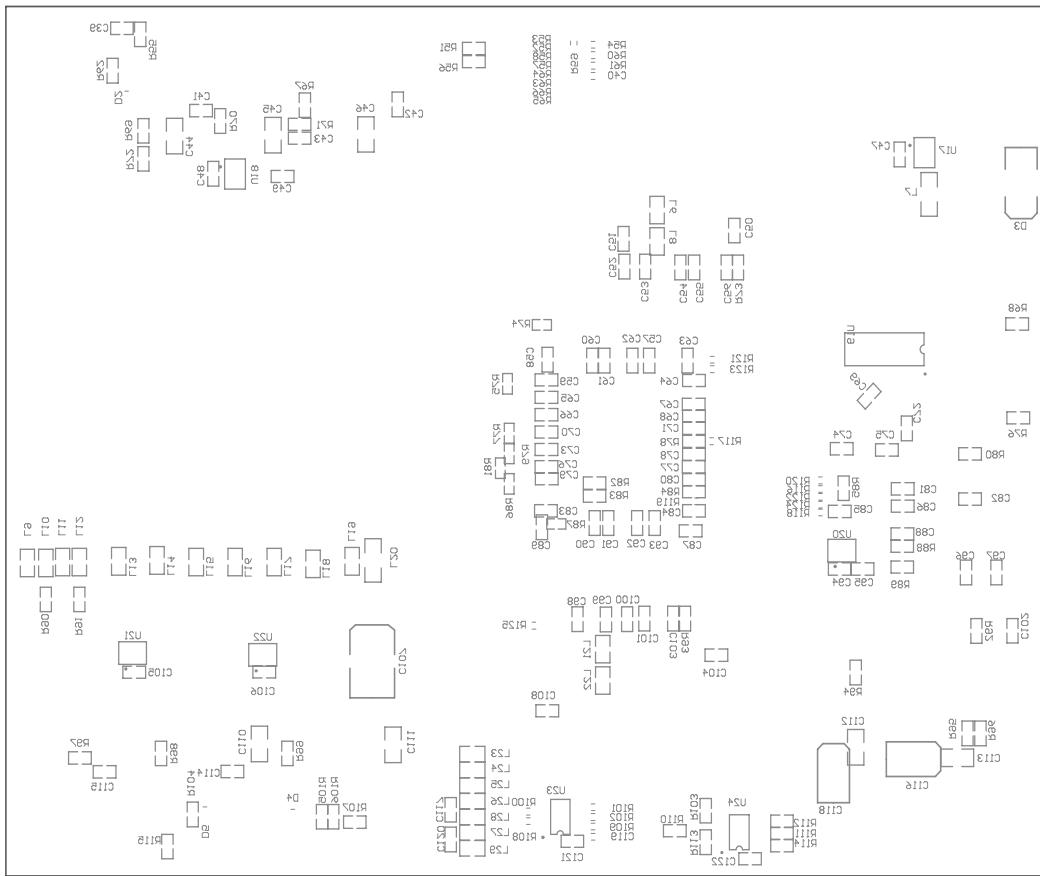
**KMB001CEVAL Layers (Continued)**



**FIGURE 14. BOTTOM LAYER**

**KMB001CEVAL Layers (Continued)****FIGURE 15. TOP OVERLAY**

## ***KMB001CEVAL Layers*** (Continued)



**FIGURE 16. BOTTOM OVERLAY**

*Intersil Corporation reserves the right to make changes in circuit design, software and/or specifications at any time without notice. Accordingly, the reader is cautioned to verify that the Application Note or Technical Brief is current before proceeding.*

For information regarding Intersil Corporation and its products, see [www.intersil.com](http://www.intersil.com)